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PROVISIONAL APPLICATION FOR PATENT COVER SHEET

This is a request for filing a PROVISIONAL APPLICATION FOR PATENT under 37 CFR 1.53(c).

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INVENTOR(S)					
Given Name (first and middle (if any))		Family Name or Surname		Residence (City and either State or Foreign Country)	
Thanhhung A		Le		10312 OAK shade Ct. Mechanicsville, VA 23116	
Additional inventors are being named on the _____ separately numbered sheets attached hereto					
TITLE OF THE INVENTION (500 characters max)					
Monitoring Apparatus For A Package					
Direct all correspondence to: CORRESPONDENCE ADDRESS					
<input checked="" type="checkbox"/> Customer Number: 31142					
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<input type="checkbox"/> Firm or Individual Name					
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Address					
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USA		301 497-1379		301 497-1309	
ENCLOSED APPLICATION PARTS (check all that apply)					
<input checked="" type="checkbox"/> Specification Number of Pages <u>8</u>					
<input checked="" type="checkbox"/> Drawing(s) Number of Sheets <u>8</u>					
<input type="checkbox"/> Application Data Sheet. See 37 CFR 1.76					
<input type="checkbox"/> CD(s), Number _____					
<input type="checkbox"/> Other (specify) _____					
METHOD OF PAYMENT OF FILING FEES FOR THIS PROVISIONAL APPLICATION FOR PATENT					
<input type="checkbox"/> Applicant claims small entity status. See 37 CFR 1.27.					
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The invention was made by an agency of the United States Government or under a contract with an agency of the United States Government.					
<input checked="" type="checkbox"/> No.					
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5585 U.S. PTO
60/587297

012004

[Page 1 of 2]

Respectfully submitted,

SIGNATURE

Donald L. Bowman

TYPED or PRINTED NAME

Donald L. Bowman

TELEPHONE

301 497-1379

Date

1/20/04

REGISTRATION NO.

46,432

(if appropriate)

Docket Number:

CPG 03-30 MB PROV

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Given Name (first and middle [if any])	Family or Surname	Residence (City and either State or Foreign Country)
Rune Karl	Haraldsson	11025 Arbor Croft Way Chester, VA 23831

[Page 2 of 2]

Number 2 of 2

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FEE TRANSMITTAL
for FY 2004

Effective 10/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT

(\$) 160.00

Complete if Known

Application Number

Filing Date

First Named Inventor

Thanhhuong N. Le

Examiner Name

Art Unit

Attorney Docket No.

CPG-03-30 MB PROU

METHOD OF PAYMENT (check all that apply)☐ Check ☐ Credit card ☐ Money Order ☐ Other ☐ None☒ Deposit Account:Deposit
Account
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MeadWestvaco Corp.

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☒ Credit any overpayments☐ Charge any additional fee(s) or any underpayment of fee(s)☐ Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.**FEE CALCULATION****1. BASIC FILING FEE**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1001 770	2001 385	Utility filing fee	
1002 340	2002 170	Design filing fee	
1003 530	2003 265	Plant filing fee	
1004 770	2004 385	Reissue filing fee	
1005 160	2005 80	Provisional filing fee	160.00

SUBTOTAL (1) (\$) 160.00

2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

Total Claims	Extra Claims	Fee from below	Fee Paid
Independent Claims	-20** =	X	
Multiple Dependent	-3** =	X	

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description
1202 18	2202 9	Claims in excess of 20
1201 86	2201 43	Independent claims in excess of 3
1203 290	2203 145	Multiple dependent claim, if not paid
1204 86	2204 43	** Reissue independent claims over original patent
1205 18	2205 9	** Reissue claims in excess of 20 and over original patent

SUBTOTAL (2) (\$)

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity Small Entity

Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1051 130	2051 65	Surcharge - late filing fee or oath	
1052 50	2052 25	Surcharge - late provisional filing fee or cover sheet	
1053 130	1053 130	Non-English specification	
1812 2,520	1812 2,520	For filing a request for <i>ex parte</i> reexamination	
1804 920*	1804 920*	Requesting publication of SIR prior to Examiner action	
1805 1,840*	1805 1,840*	Requesting publication of SIR after Examiner action	
1251 110	2251 55	Extension for reply within first month	
1252 420	2252 210	Extension for reply within second month	
1253 950	2253 475	Extension for reply within third month	
1254 1,480	2254 740	Extension for reply within fourth month	
1255 2,010	2255 1,005	Extension for reply within fifth month	
1401 330	2401 165	Notice of Appeal	
1402 330	2402 165	Filing a brief in support of an appeal	
1403 290	2403 145	Request for oral hearing	
1451 1,510	1451 1,510	Petition to institute a public use proceeding	
1452 110	2452 55	Petition to revive - unavoidable	
1453 1,330	2453 665	Petition to revive - unintentional	
1501 1,330	2501 665	Utility issue fee (or reissue)	
1502 480	2502 240	Design issue fee	
1503 640	2503 320	Plant issue fee	
1460 130	1460 130	Petitions to the Commissioner	
1807 50	1807 50	Processing fee under 37 CFR 1.17(q)	
1806 180	1806 180	Submission of Information Disclosure Stmt	
8021 40	8021 40	Recording each patent assignment per property (times number of properties)	
1809 770	2809 385	Filing a submission after final rejection (37 CFR 1.129(a))	
1810 770	2810 385	For each additional invention to be examined (37 CFR 1.129(b))	
1801 770	2801 385	Request for Continued Examination (RCE)	
1802 900	1802 900	Request for expedited examination of a design application	

Other fee (specify)

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$)

SUBMITTED BY

Name (Print/Type)

Donald L. Bowman

Registration No.
(Attorney/Agent)

46,432

(Complete if applicable)

Telephone

301 497-1379

Signature

D. Bowman

Date

1/20/04

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MONITORING APPARATUS FOR A PACKAGE

BACKGROUND OF THE INVENTION

[0001] The invention teaches an apparatus for monitoring the removal of contents from a package, such as a pharmaceutical package.

[0002] The use of blisters to package items, such as pharmaceutical pills, is well known. United States Patent No. 6,244,462 issued to Ehrensvar et al and assigned to Cypak illustrates some of the features of an electronic medication dispense sensing device to monitor the removal of pills from a blister package. However the Ehrensvar patent has several shortcomings. First, the sheet-like envelope used to print the electrical circuit is difficult to fold and retain in a folded position. Second, the envelope limits the number of package shapes and configurations due to bulk of the folded envelope. Third, after the blister package is secured to the envelope it is difficult to test the monitoring circuit and remove the blister package and its contents if the circuit fails. For at least these reasons, there is a need to improve the design and method of making a monitoring apparatus for a package.

SUMMARY OF THE INVENTION

[0003] The invention teaches an apparatus for monitoring the removal of contents from a package and a method of making the apparatus.

BRIEF DESCRIPTION OF THE FIGURES

[0004] Additional features of the invention will become more apparent in the description below contain herein and can be further understood by reading the accompanying figures, wherein like characters represent like parts throughout the several views.

[0005] Figure 1 is a top plan view of a monitoring substrate according to the invention.

[0006] Figure 2 is a top plan view of a monitoring substrate with an monitoring circuit formed on the substrate.

[0007] Figure 3 is a top plan view of monitoring substrate with a digital processing unit in communication with the monitoring circuit.

[0008] Figure 4 is a top plan view of a package substrate according to the invention.

[0009] Figure 4B is a bottom plan view of the other side of said package substrate of Figure 4.

[0010] Figure 5 is a perspective view of a blister package.

[0011] Figure 6 is a top plan view of a blister package inserted into the package substrate.

[0012] Figure 7 is a perspective view of the monitored package partially inserted into an outer sleeve.

[0013] Figure 8 is a top plan view of another embodiment according to the invention.

DESCRIPTION OF THE INVENTION

[0014] Figure 1 illustrates a monitoring substrate 10 formed from any suitable material, such as paper, paperboard, composite material, plastics, etc. An exemplary material is formed from EasySeal Plus, manufactured by MeadWestvaco Corporation, Stamford, CT. Optional perforated regions 12, hereinafter referred to as "gates" are illustrated formed on a first surface 11 of the substrate 10. These gates 12 assist with removal of items from the package. In addition, optional embossed or partially raised or indented areas 12, are also illustrated.

[0015] Figure 2 illustrates an exemplary monitoring apparatus formed on the top surface 11 of the substrate 10. In an exemplary embodiment, an electrically conductive circuit is formed on the substrate to form a monitoring substrate 20. The electrical circuit is formed of any suitable conductive material, such as conductive ink or conductive metals or any suitable combination. An exemplary circuit design includes a ground region 21 as illustrated on one end of the

monitoring substrate 20. Connection regions 22 for connecting to a digital processing unit 30 (see Figure 3) to the electrical circuit are also illustrated. Monitoring circuits 23 leading to each gate region 12 are illustrated. A conductive region 24 is illustrated over each gate 12. An optional enlarged conductive region 26 is illustrated toward the lower portion of the monitoring substrate 20. The enlarged region 26 could facilitate folding the monitoring substrate 20 in that region. An optional electrical switch 28 region is illustrated covering the embossed areas 13 of the monitoring substrate. The electrical switches 28 allow additional digital information to be collected from the monitoring substrate 20 and will be discussed in more detail below. It is to be understood that if a conductive material, such as an Aluminum foil backed blister package is secured directly to the monitoring substrate over the electrical circuit than a dielectric layer must be placed between the two conductive materials.

[0016] Figure 3 illustrates an exemplary digital processing unit 32 in electrical communication with the monitoring substrate 20 to form a monitoring apparatus 30. The digital processing unit 32 could comprise numerous configurations. For example, the processing unit 32 could include one of more of the following features, an internal or external power source, such as a battery, a memory storage device, a digital processing unit, an electrical signal output unit, a digital signal output device, such as audio device or visual display, an antenna, a modem, a clock, a processor controller, transmitter, one or more computer programs, as well as other well known digital and analog devices.

[0017] Figure 4 illustrates an exemplary packaging substrate 40 with a first surface 41. Apertures 42 are illustrated in a central region of the packaging substrate 40. Optional conductive regions 44 are illustrated at the lower end of the substrate 40. Optional aperture 43 is also illustrated to allow the digital processing unit 32 to extend through the package substrate 40.

Figure 4B illustrates the opposite side 45 of the packaging substrate. Text can be added to this surface of the substrate, such as the question "How do you feel since taking your last pill?" and answers, "Better," "Worse," "Same," and "Not sure" printed adjacent to the various conductive regions 44.

[0018] Figure 5 illustrates an exemplary blister package 50. A blister has a top surface 52 with a blister cells 53 extending from the top surface 52 with an end region 56. An item, such as a pill, is retained in the blister cell 53 by a backing material 54 secured to the bottom surface of the blister. The blister is typically formed from a substrate such as a thermo-formed plastic. A backing material 54 is typically made from foil, paperboard or other suitable material and is secured to the bottom of the blister. If the backing material 54 is conductive a dielectric layer must separate the backing material 54 from the conductive surfaces of the monitoring apparatus 30.

[0019] Figure 6 illustrates a blister package 50 secured to the packaging substrate 40 to form a package 60. The blister cells 53 ideally extend through the package substrate 40. The blister package 50 can optionally be secured to the packaging substrate 40 by adhesive or other suitable means.

[0020] According to a first exemplary embodiment, the package 60 is secured to the monitoring apparatus 30. The digital processing unit 32 ideally extends through the opening 43 of the package 60. The electrical circuits of the monitoring apparatus 30 are aligned with the blister cells 53 and the conductive regions 44 of the package 60. To remove an item 56 from the monitored package 60, the item 56 must be pushed through the backing material 54, and through the gate region 24 of the monitoring apparatus 20. In an exemplary method of operation, the digital processing unit 32, continuously or periodically sends a signal to each gate region 24. If

an item 56 has been removed, the resistance of an individual circuit will be high, as the gate 12 and the conductive material 24 have been removed. Thus little or no electrical signal will be returned to the digital processing unit 32 via the ground region 21. If the digital processing unit 32 is programmed with specific resistance levels, than the processing unit 32 can determine if an item 56 has been removed or not from the package 60 by measuring the resistance level of a particular monitoring circuit. By keeping track of which items have been removed the processing unit 32 can monitor and detect each successive removal. The digital processing unit 32 could also record the time and store it to a memory unit or transmit it to an external device (not illustrated). In addition, the unit 32 can record any closure of the switch region 28 on the monitoring apparatus. The switch 28 can be closed, by pressing or manipulating the conductive regions 44 on the monitored package 60. Switch closure 28 information can be stored in the memory or transmitted to external devices as well. The digital processing unit can limit the time period to monitor movement of the switch or limit the duration of time that it records switch movement to for example 1 minute or less. By tracking the removal of an item 56 and recording answers to the questions printed on the package, via the switches 28, input on the effectiveness of a pill, such a drug undergoing trials, can be recorded. It is to be understood that the above description is but one of many way to program and monitor the contents of the package 60.

[0021] Figure 7 illustrates the package 60 partially extended from an optional outer sleeve 100. It is to be understood that the monitored package could be further packaged into many different configured outer sleeves 100. Ideally, the monitored package 60 would be placed in a child resistant outer sleeve. An exemplary configuration of the monitored package 60 and outer sleeve 100 could include a Dosepak (TM) container design manufactured by MeadWestvaco Corporation of Stamford, CT more fully described in United States Patent No. 6,047,829. It is to

be understood that the outer sleeve could further contain communication gear, an external power source, and numerous apparatuses to allow it to communicate with a computer or network, such as a phone.

[0022] It is to be understood that a one piece substrate with two regions 110, 140 could be used to secure a blister package (not illustrated) between the substrates 110, 140. A monitoring substrate 30 (not illustrated) as described above could then be secured to the base of substrate 140. In this embodiment, no dielectric layer would have to be placed between the backing material 54 of the blister package 50 and the electrical circuit on the monitoring substrate 30.

[0023] Once given the above disclosure, many other features and additional embodiments of the invention will become apparent to the skilled artisan. Such features and additional embodiments are therefore, considered to be a part of this invention, the scope of which is to be determined by the following claims.

CLAIMS

1. An apparatus comprising a monitoring substrate with a patterned conductive region further comprising a ground region; a monitoring circuit, a digital processor communication region.
2. The apparatus of claim 1 further comprising at least one input region.
3. The apparatus of claim 1 wherein said monitoring substrate is in electrical communication with a digital processing unit.
4. An apparatus comprising:
a monitoring substrate with a patterned conductive region further comprising a ground region; a monitoring circuit, and a digital processor communication region; and
a digital processing unit in electrical communication with said monitoring substrate.
5. An apparatus comprising:
a monitoring substrate with a patterned conductive region further comprising a ground region; a monitoring circuit, and a digital processor communication region;
a digital processing unit in electrical communication with said monitoring substrate; and
a blister package comprising a one or more blister cells secured to said monitoring substrate wherein said monitoring circuits are aligned with said blister cells and said monitoring circuits are configured so that they are substantially destroyed when an item is removed from the blister package.
6. The apparatus of claim 5 wherein a dielectric material separates the back of said blister package from any conductive portion of said monitoring substrate.
7. The apparatus of claim 6 wherein said patterned conductive regions comprise conductive ink.

ABSTRACT

The invention teaches an apparatus for monitoring the removal of contents from a package and a method of making the apparatus.

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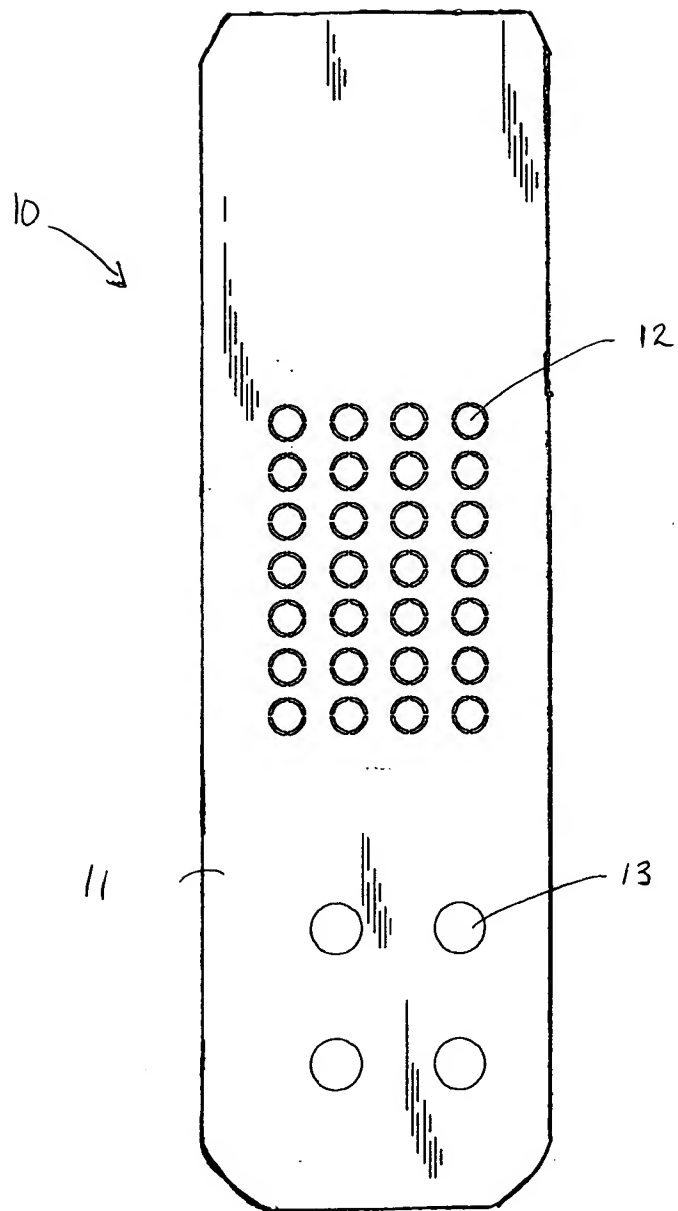


Figure 2

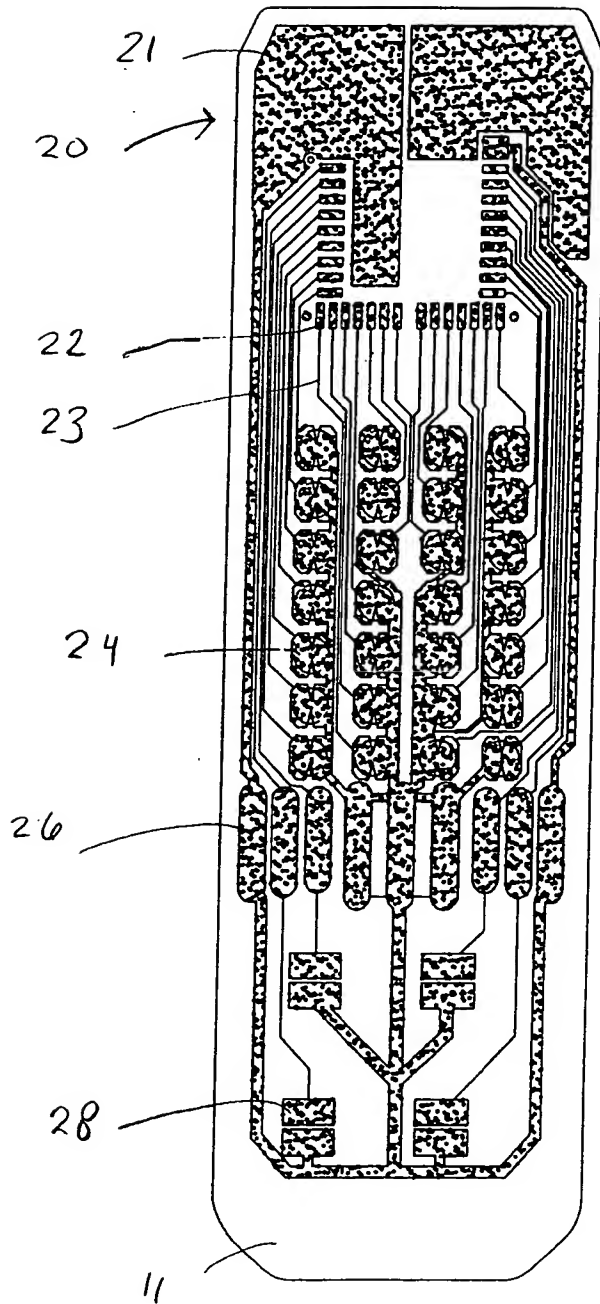


Figure 3

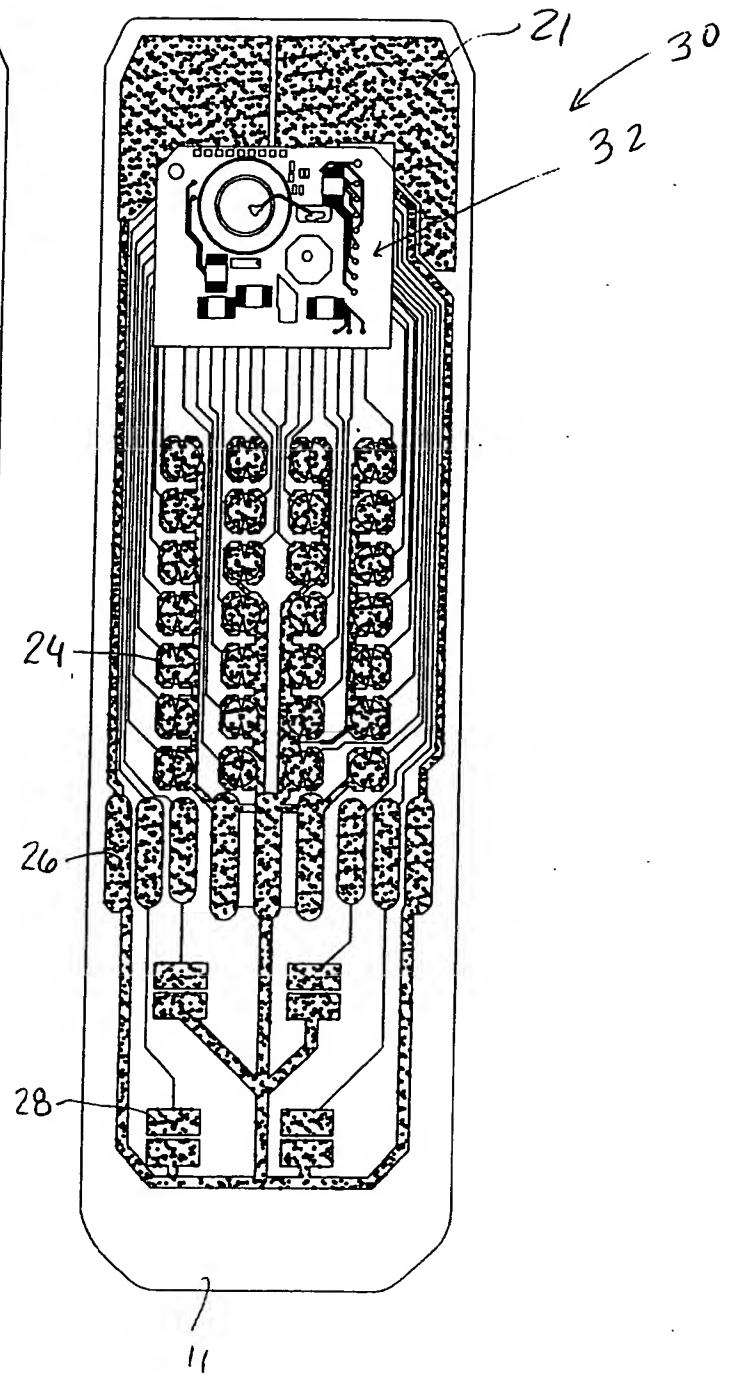


Figure 4

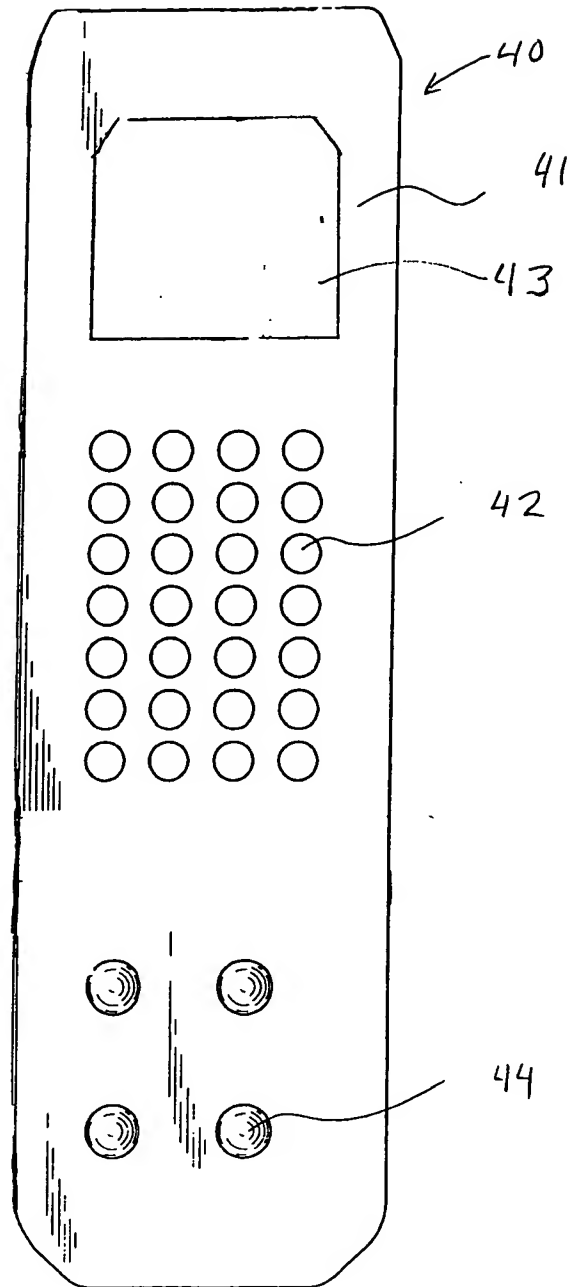


Figure 4B

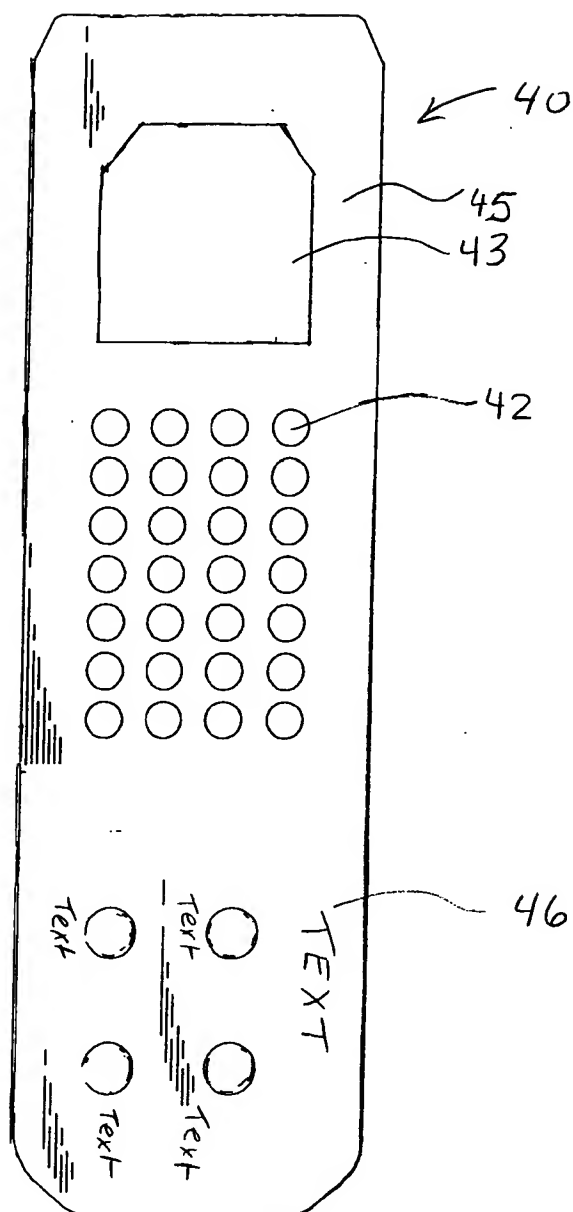


Figure 5

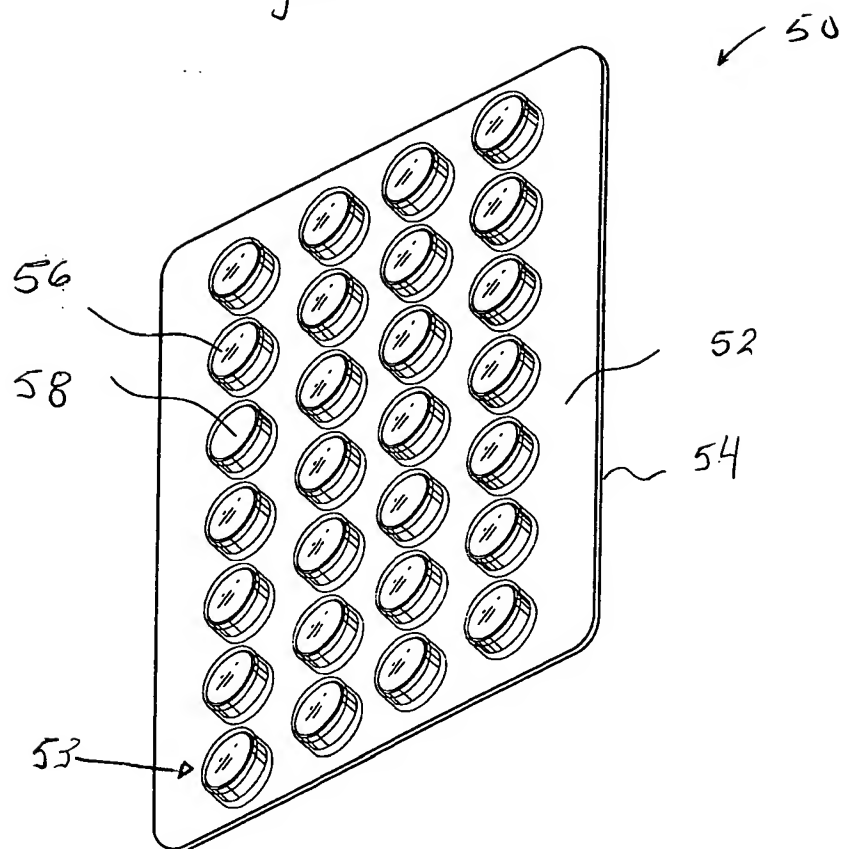


Figure 6

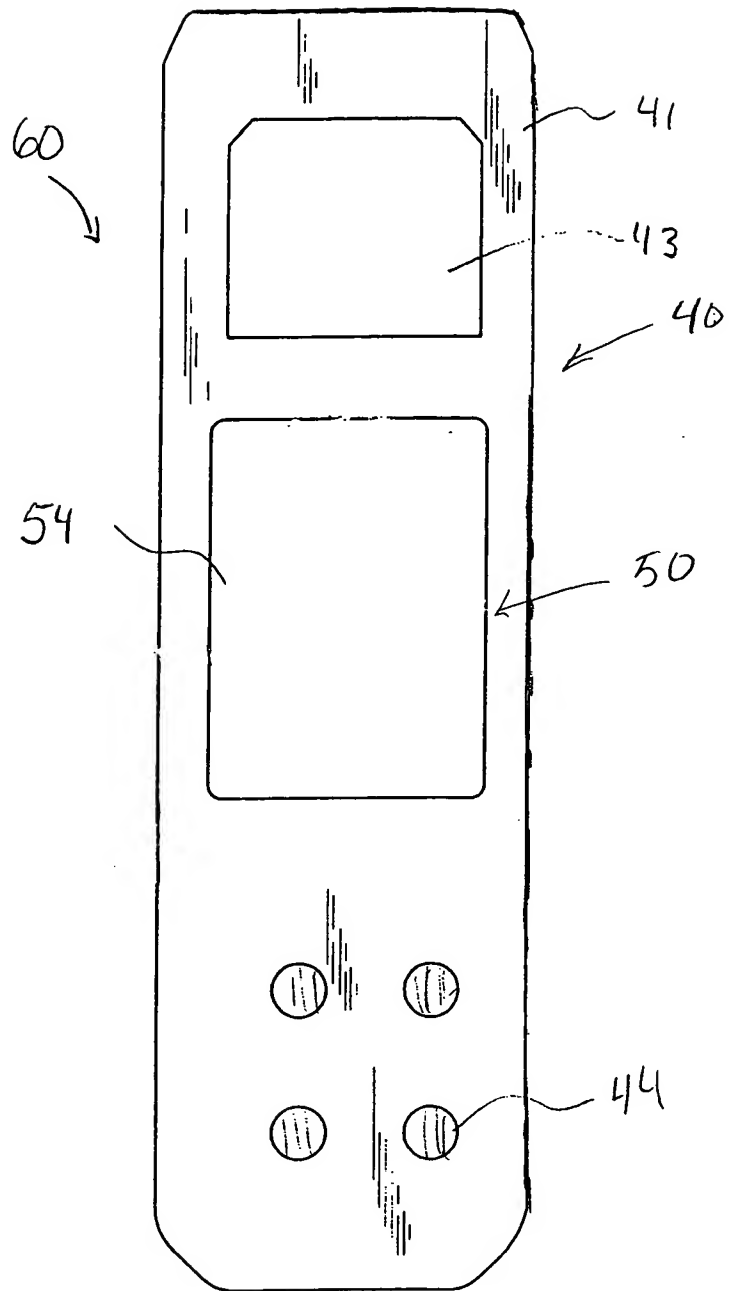


Figure 7

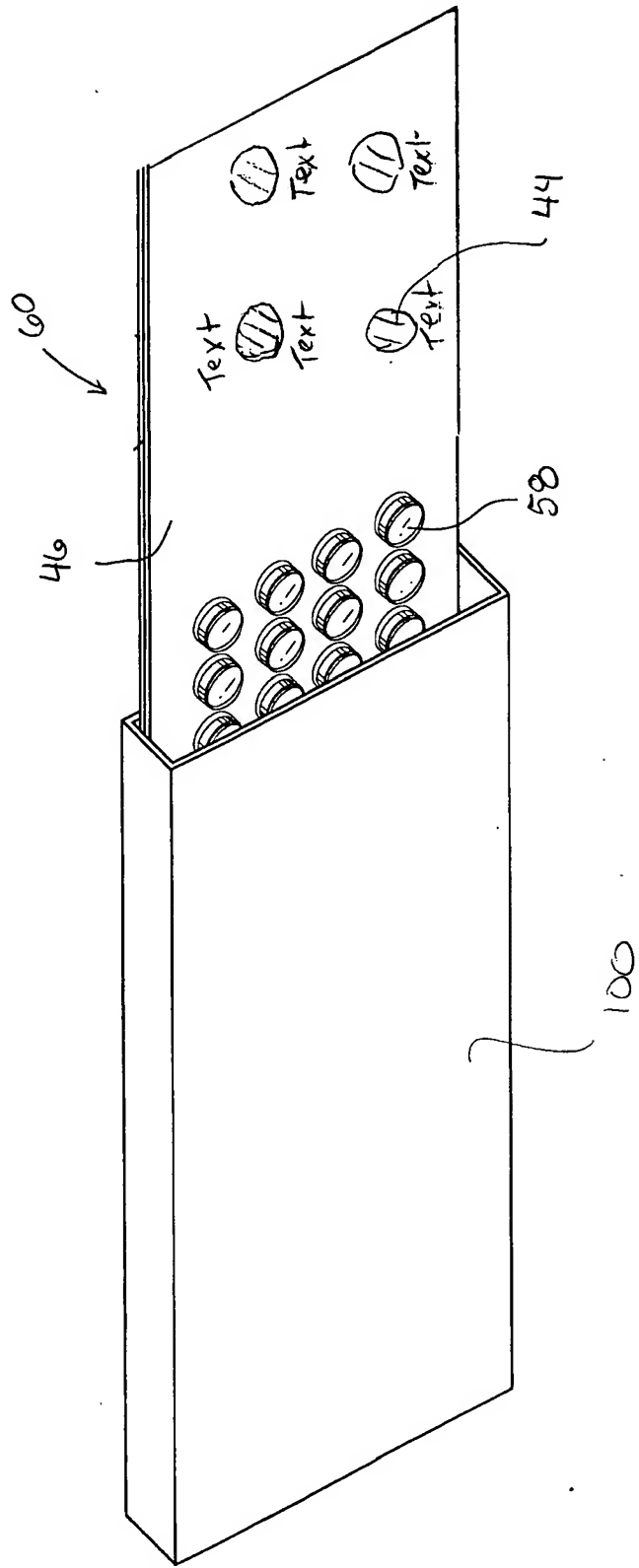


Figure 8

